

LMR14203

SIMPLE SWITCHER® 42Vin, 0.3A Step-Down Voltage Regulator in SOT-23

Features

- Input voltage range of 4.5V to 42V
- Output voltage range of 0.765V to 34V
- Output current up to 0.3A
- 1.25 MHz switching frequency
- Low shutdown I_q , 16 μ A typical
- Short circuit protected
- Internally compensated
- Soft-start function
- Thin SOT23-6 package (2.97 x 1.65 x 1mm)
- Fully enabled for WEBENCH® Power Designer

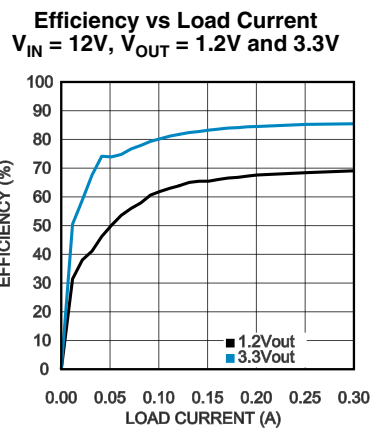
Applications

- Point-of-Load Conversions from 5V, 12V, and 24V Rails
- Space Constrained Applications
- Battery Powered Equipment
- Industrial Distributed Power Applications
- Power Meters
- Portable Hand-Held Instruments

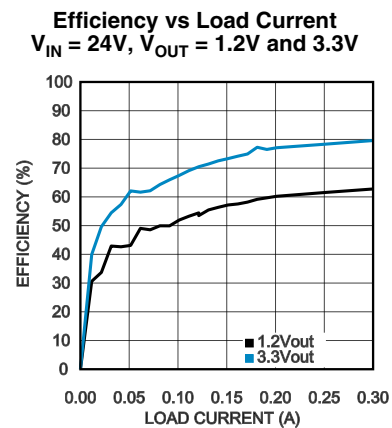
Performance Benefits

- Tight accuracy for powering digital ICs
- Extremely easy to use
- Tiny overall solution reduces system cost

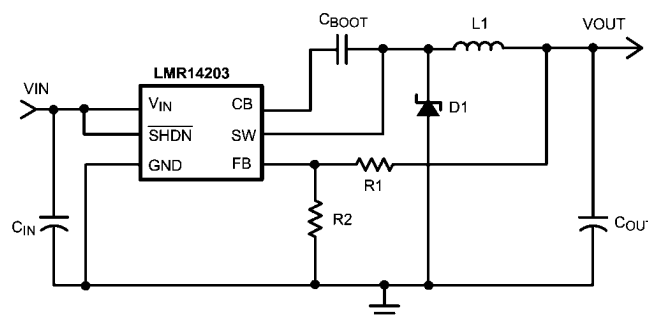
System Performance



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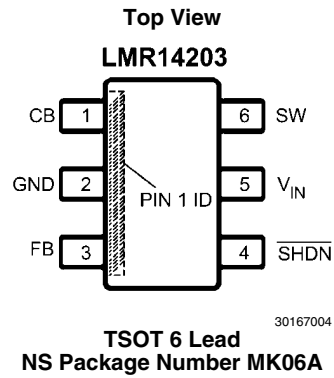


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Connection Diagram



Ordering Information

| Order Number | Spec. | Package Type | NSC Package Drawing | Top Mark | Supplied As |
|--------------|-------|--------------|---------------------|----------|---------------------------|
| LMR14203XMKE | NOPB | TSOT-6 | MK06A | SJ3B | 250 Units, Tape and Reel |
| LMR14203XMK | | | | | 1000 Units, Tape and Reel |
| LMR14203XMKX | | | | | 3000 Units, Tape and Reel |

Pin Descriptions

| Pin | Name | Function |
|-----|-------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 1 | CB | SW FET gate bias voltage. Connect C_{BOOT} cap between CB and SW. |
| 2 | GND | Ground connection. |
| 3 | FB | Feedback pin: Set feedback voltage divider ratio with $V_{OUT} = V_{FB} (1 + (R1/R2))$. Resistors should be in the 100-10K range to avoid input bias errors. |
| 4 | \overline{SHDN} | Logic level shutdown input. Pull to GND to disable the device and pull high to enable the device. If this function is not used tie to V_{IN} or leave open. |
| 5 | V_{IN} | Power input voltage pin: 4.5V to 42V normal operating range. |
| 6 | SW | Power FET output: Connect to inductor, diode, and C_{BOOT} cap. |

Absolute Maximum Ratings *(Note 1)*

If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.

| | |
|-----------------------------------|--------------------------------|
| V_{IN} | -0.3V to +45V |
| SHDN | -0.3V to $(V_{IN}+0.3V) < 45V$ |
| SW Voltage | -0.3V to +45V |
| CB Voltage above SW Voltage | 7V |
| FB Voltage | -0.3V to +5V |
| Maximum Junction Temperature | 150°C |
| Power Dissipation <i>(Note 2)</i> | Internally Limited |

For soldering specifications: see product folder at www.national.com and www.national.com/ms/MS/MS-SOLDERING.pdf

ESD Susceptibility *(Note 3)*

Human Body Model

1.5 kV

Operating Conditions

| | |
|------------------------------------------------------|-----------------|
| Operating Junction Temperature Range <i>(Note 4)</i> | -40°C to +125°C |
| Storage Temperature | -65°C to +150°C |
| Input Voltage V_{IN} | 4.5V to 42V |
| SW Voltage | Up to 42V |

Electrical Characteristics

Specifications in standard type face are for $T_J = 25^\circ\text{C}$ and those with **boldface type** apply over the full **Operating Temperature Range** ($T_J = -40^\circ\text{C}$ to $+125^\circ\text{C}$). Minimum and Maximum limits are guaranteed through test, design, or statistical correlation. Typical values represent the most likely parametric norm at $T_J = +25^\circ\text{C}$, and are provided for reference purposes only. Unless otherwise stated the following conditions apply: $V_{IN} = 12V$.

| Symbol | Parameter | Conditions | Min <i>(Note 4)</i> | Typ <i>(Note 5)</i> | Max <i>(Note 4)</i> | Units |
|--------------|---------------------------------|-----------------------------------|---------------------|---------------------|---------------------|---------------|
| I_Q | Quiescent current | SHDN = 0V | | 16 | 40 | μA |
| | | Device On, Not Switching | | 1.30 | 1.75 | mA |
| | | Device On, No Load | | 1.35 | 1.85 | |
| $R_{DS(ON)}$ | Switch ON resistance | <i>(Note 6)</i> | | 0.9 | 1.6 | Ω |
| I_{LSW} | Switch leakage current | $V_{IN} = 42V$ | | 0.0 | 0.5 | μA |
| I_{CL} | Switch current limit | <i>(Note 7)</i> | | 525 | | mA |
| I_{FB} | Feedback pin bias current | <i>(Note 8)</i> | | 0.1 | 1.0 | μA |
| V_{FB} | FB Pin reference voltage | | 0.747 | 0.765 | 0.782 | V |
| t_{MIN} | Minimum ON time | | | 100 | | ns |
| f_{SW} | Switching frequency | $V_{FB} = 0.5V$ | 0.95 | 1.25 | 1.50 | MHz |
| | | $V_{FB} = 0V$ | | 0.35 | | |
| D_{MAX} | Maximum duty cycle | | 81 | 87 | | % |
| V_{UVP} | Undervoltage lockout thresholds | On threshold | 4.4 | 3.7 | | V |
| | | Off threshold | | 3.5 | 3.25 | |
| V_{SHDN} | Shutdown threshold | Device on | 2.3 | 1.0 | | V |
| | | Device off | | 0.9 | 0.3 | |
| I_{SHDN} | Shutdown pin input bias current | $V_{SHDN} = 2.3V$ <i>(Note 8)</i> | | 0.05 | 1.5 | μA |
| | | $V_{SHDN} = 0V$ | | 0.02 | 1.5 | |

THERMAL SPECIFICATIONS

| | | | | | | |
|-----------------|---------------------------------------------------------|-----------------|--|-----|--|--------------------|
| $R_{\theta JA}$ | Junction-to-Ambient Thermal Resistance, TSOT-6L Package | <i>(Note 9)</i> | | 121 | | $^\circ\text{C/W}$ |
|-----------------|---------------------------------------------------------|-----------------|--|-----|--|--------------------|

Note 1: Absolute maximum ratings are limits beyond which damage to the device may occur. Operating Ratings are conditions for which the device is intended to be functional, but device parameter specifications may not be guaranteed. For guaranteed specifications and test conditions, see the Electrical Characteristics.

Note 2: The maximum allowable power dissipation is a function of the maximum junction temperature, $T_{J(MAX)}$, the junction-to-ambient thermal resistance, θ_{JA} , and the ambient temperature, T_A . The maximum allowable power dissipation at any ambient temperature is calculated using: $P_D (MAX) = (T_{J(MAX)} - T_A) / \theta_{JA}$. Exceeding the maximum allowable power dissipation will cause excessive die temperature, and the regulator will go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage. Thermal shutdown engages at $T_J=175^\circ\text{C}$ (typ.) and disengages at $T_J=155^\circ\text{C}$ (typ).

Note 3: Human Body Model, applicable std. JESD22-A114-C.

Note 4: All limits guaranteed at room temperature (standard typeface) and at temperature extremes (bold typeface). All room temperature limits are 100% production tested. All limits at temperature extremes are guaranteed via correlation using standard Statistical Quality Control (SQC) methods. All limits are used to calculate Average Outgoing Quality Level (AOQL).

Note 5: Typical numbers are at 25°C and represent the most likely norm.

Note 6: Includes the bond wires, $R_{DS(ON)}$ from V_{IN} pin to SW pin.

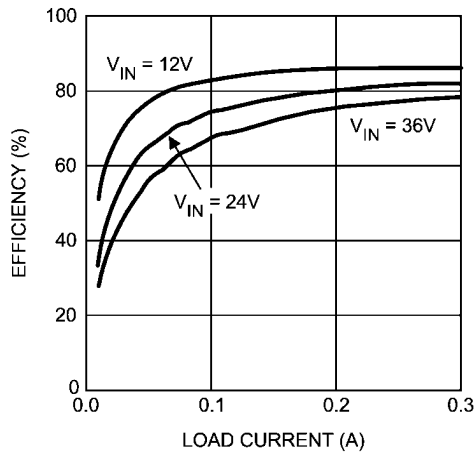
Note 7: Current limit at 0% duty cycle.

Note 8: Bias currents flow into pin.

Note 9: All numbers apply for packages soldered directly onto a 3" x 3" PC board with 2 oz. copper on 4 layers in still air in accordance to JEDEC standards. Thermal resistance varies greatly with layout, copper thickness, number of layers in PCB, power distribution, number of thermal vias, board size, ambient temperature, and air flow.

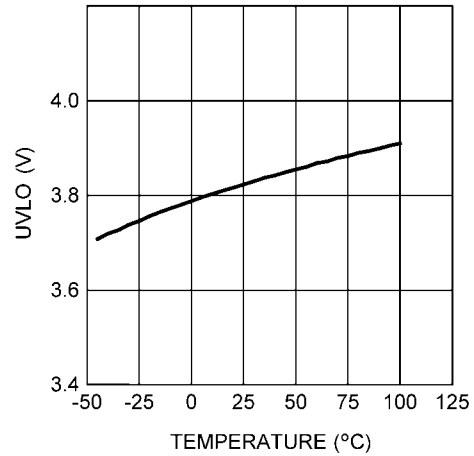
Typical Performance Characteristics

Efficiency vs. Load Current
($V_{OUT} = 3.3V$)



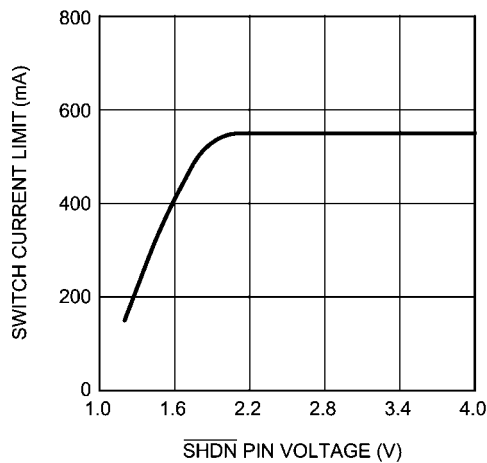
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Input UVLO Voltage vs. Temperature



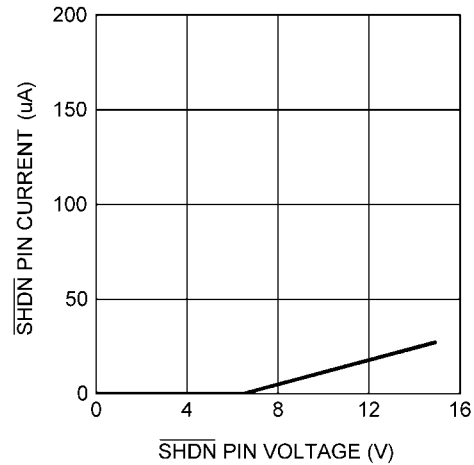
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Switch Current Limit vs. \overline{SHDN} Pin Voltage
(Soft-start Implementation)



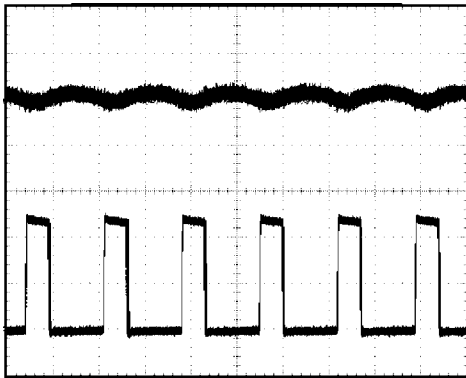
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\overline{SHDN} Pin Current vs. \overline{SHDN} Pin Voltage



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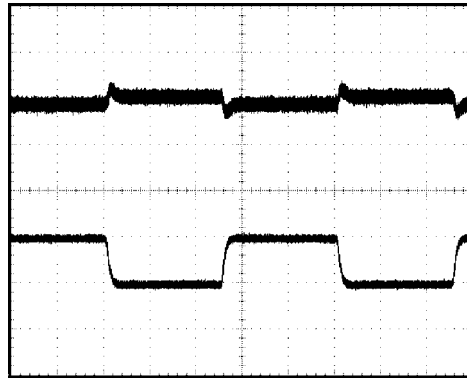
Switching Node and Output Voltage Waveforms



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$V_{IN} = 12V$, $V_{OUT} = 3.3V$, $I_{OUT} = 200 mA$
 Top trace: V_{OUT} , 10 mV/div, AC Coupled
 Bottom trace: SW, 5V/div, DC Coupled
 T = 1 μs /div

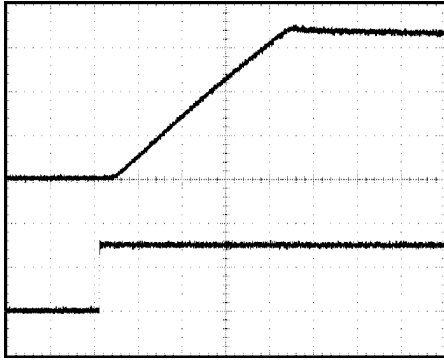
Load Transient Waveforms



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$V_{IN} = 12V$, $V_{OUT} = 3.3V$, $I_{OUT} = 300 mA$ to $200 mA$ to $300 mA$
 Top trace: V_{OUT} , 20 mV/div, AC Coupled
 Bottom trace: I_{OUT} , 100 mA/div, DC Coupled
 T = 200 μs /div

Start-Up Waveform



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$V_{IN} = 12V$, $V_{OUT} = 3.3V$, $I_{OUT} = 50\text{ mA}$
Top trace: V_{OUT} , 1V/div, DC Coupled
Bottom trace: \overline{SHDN} , 2V/div, DC Coupled
T = 40 $\mu\text{s}/\text{div}$

INDUCTOR SELECTION

The most critical parameters for the inductor are the inductance, peak current, and the DC resistance. The inductance is related to the peak-to-peak inductor ripple current, the input and the output voltages.

$$L = \frac{(V_{IN} - V_{OUT})V_{OUT}}{V_{IN} \times I_{RIPPLE} \times f_{SW}}$$

A higher value of ripple current reduces inductance, but increases the conductance loss, core loss, and current stress for the inductor and switch devices. It also requires a bigger output capacitor for the same output voltage ripple requirement. A reasonable value is setting the ripple current to be 30% of the DC output current. Since the ripple current increases with the input voltage, the maximum input voltage is always used to determine the inductance. The DC resistance of the inductor is a key parameter for the efficiency. Lower DC resistance is available with a bigger winding area. A good tradeoff between the efficiency and the core size is letting the inductor copper loss equal 2% of the output power. See AN-1197 for more information on selecting inductors. A good starting point for most applications is a 10 μ H to 22 μ H with a 0.7A or greater current rating for the LMR14203. Using such a rating will enable the LMR14203 to current limit without saturating the inductor. This is preferable to the device going into thermal shutdown mode and the possibility of damaging the inductor if the output is shorted to ground or other longterm overload.

OUTPUT CAPACITOR

The selection of C_{OUT} is driven by the maximum allowable output voltage ripple. The output ripple in the constant frequency, PWM mode is approximated by: $V_{RIPPLE} = I_{RIPPLE} (ESR + (1/(8f_{SW}C_{OUT})))$. The ESR term usually plays the dominant role in determining the voltage ripple. Low ESR ceramic capacitors are recommended. Capacitors in the range of 22 μ F-100 μ F are a good starting point with an ESR of 0.1 Ω or less.

BOOTSTRAP CAPACITOR

A 0.15 μ F ceramic capacitor or larger is recommended for the bootstrap capacitor (C_{BOOT}). For applications where the input voltage is less than twice the output voltage a larger capacitor is recommended, generally 0.15 μ F to 1 μ F to ensure plenty of gate drive for the internal switches and a consistently low R_{DSON} .

SOFT-START COMPONENTS

The LMR14203 has circuitry that is used in conjunction with the SHDN pin to limit the inrush current on start-up of the DC/DC switching regulator. The SHDN pin in conjunction with a

RC filter is used to tailor the soft-start for a specific application. When a voltage applied to the SHDN pin is between 0V and up to 2.3V it will cause the cycle by cycle current limit in the power stage to be modulated for minimum current limit at 0V up to the rated current limit at 2.3V. Thus controlling the output rise time and inrush current at startup. The resistor value should be selected so the current sourced into the SHDN pin will be greater than the leakage current of the SHDN pin (1.5 μ A) when the voltage at SHDN is equal or greater than 2.3V.

SHUTDOWN OPERATION

The SHDN pin of the LMR14203 is designed so that it may be controlled using 2.3V or higher logic signals. If the shutdown function is not to be used the SHDN pin may be tied to V_{IN} . The maximum voltage to the SHDN pin should not exceed 42V. If the use of a higher voltage is desired due to system or other constraints it may be used, however a 100 k Ω or larger resistor is recommended between the applied voltage and the SHDN pin to protect the device.

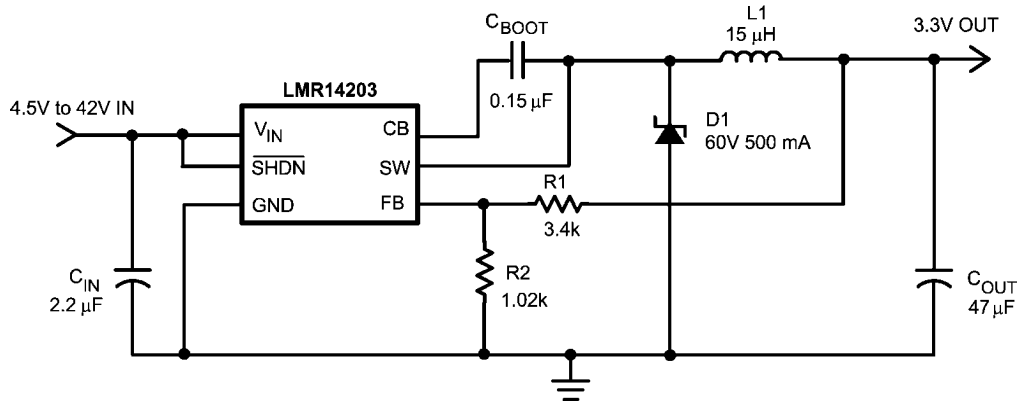
SCHOTTKY DIODE

The breakdown voltage rating of the diode (D1) is preferred to be 25% higher than the maximum input voltage. The current rating for the diode should be equal to the maximum output current for best reliability in most applications. In cases where the duty cycle is greater than 50%, the average diode current is lower. In this case it is possible to use a diode with a lower average current rating, approximately $(1-D)I_{OUT}$, however the peak current rating should be higher than the maximum load current. A 0.5A to 1A rated diode is a good starting point.

LAYOUT CONSIDERATIONS

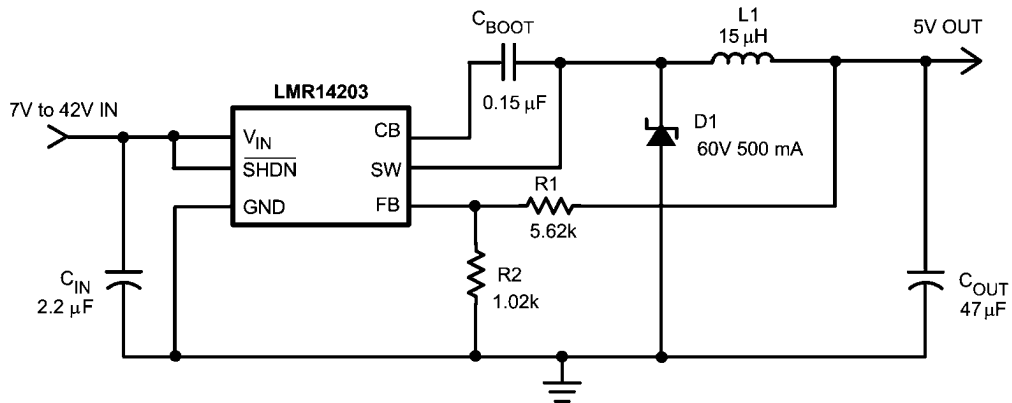
To reduce problems with conducted noise pick up, the ground side of the feedback network should be connected directly to the GND pin with its own connection. The feedback network, resistors R1 and R2, should be kept close to the FB pin, and away from the inductor to minimize coupling noise into the feedback pin. The input bypass capacitor C_{IN} must be placed close to the V_{IN} pin. This will reduce copper trace resistance which effects input voltage ripple of the IC. The inductor L1 should be placed close to the SW pin to reduce EMI and capacitive coupling. The output capacitor, C_{OUT} should be placed close to the junction of L1 and the diode D1. The L1, D1, and C_{OUT} trace should be as short as possible to reduce conducted and radiated noise and increase overall efficiency. The ground connection for the diode, C_{IN} , and C_{OUT} should be as small as possible and tied to the system ground plane in only one spot (preferably at the C_{OUT} ground point) to minimize conducted noise in the system ground plane. For more detail on switching power supply layout considerations see Application Note AN-1149: *Layout Guidelines for Switching Power Supplies*.

Typical Applications



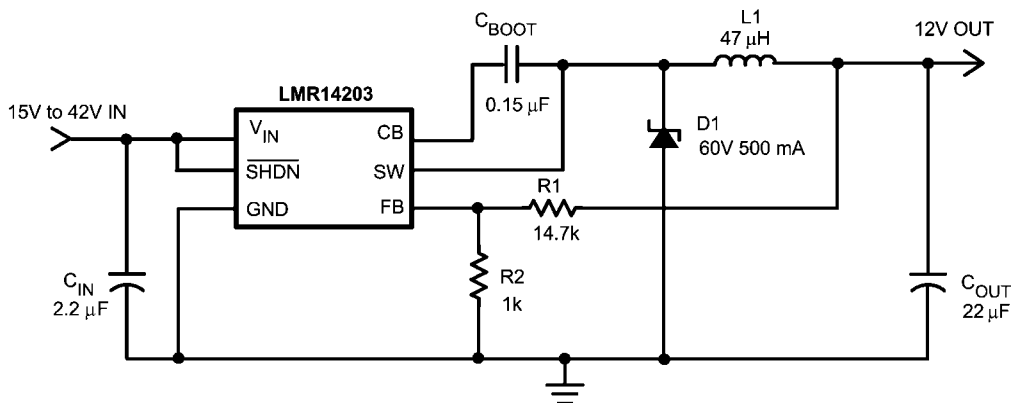
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FIGURE 1. Application Circuit, 3.3V Output



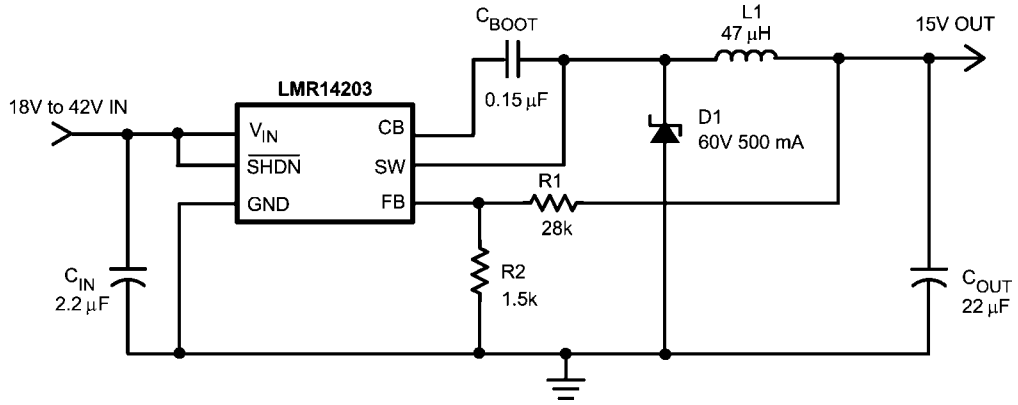
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FIGURE 2. Application Circuit, 5V Output



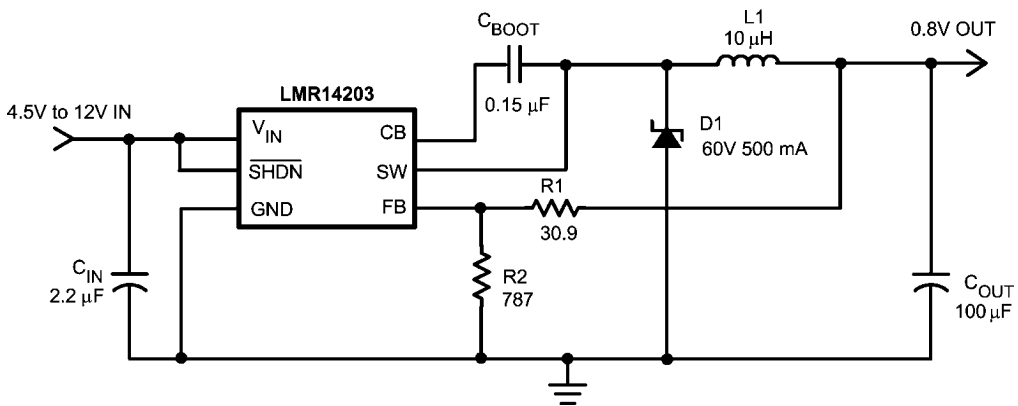
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FIGURE 3. Application Circuit, 12V Output



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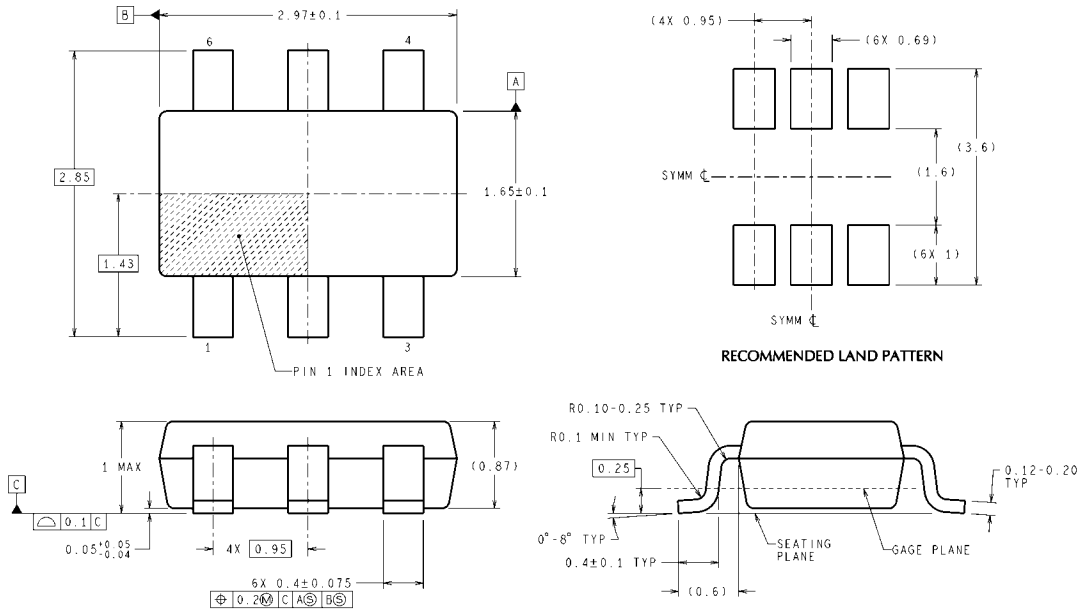
FIGURE 4. Application Circuit, 15V Output



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FIGURE 5. Application Circuit, 0.8V Output

Physical Dimensions inches (millimeters) unless otherwise noted



DIMENSIONS ARE IN MILLIMETERS

MK06A (Rev E)

TSOT 6 Pin Package (MK)
For Ordering, Refer to Ordering Information Table
NS Package Number MK06A

Notes

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